



# World's First Polymorphic Computer – MONARCH

- System on a Chip
  - 64 GFLOPS
  - 12 MBytes RAM
  - 43 GBytes/s I/O rate
  - Memory BW
    - on chip >60 GBytes/s
    - off-chip >10 GBytes/s
- Power sustained 5 GFLOPS/W
- Standard interfaces
  - Serial Rapid IO – 2 ports
  - DDR2 – 2 ports
- Key physical characteristics
  - 18.76 mm X 18.76 mm
  - 1.5 Km wiring
  - 280 Million cells



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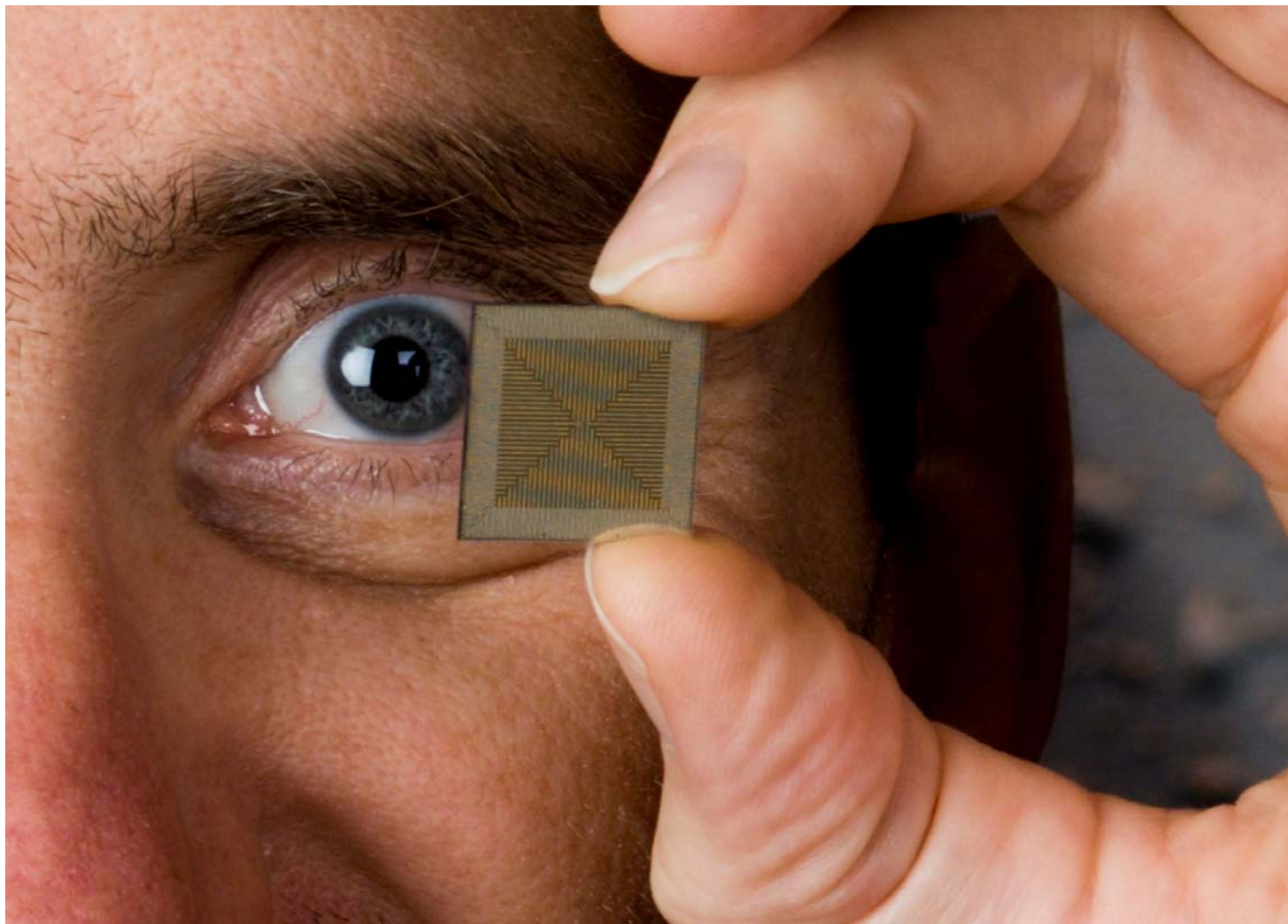


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# MONARCH Silicon is here TODAY!



**First Pass Functional Silicon**



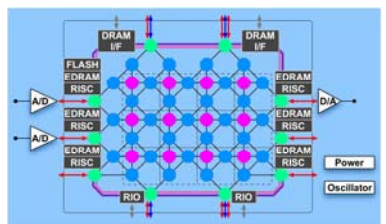


# What is MONARCH?

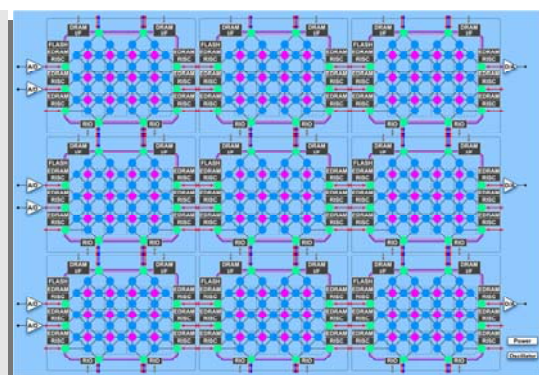
## MORphable Networked micro-ARCHitecture

- ◆ Single, programmable chip type which can replace custom ASICs
  - Saves \$20-30M development cost and 18-36 months of development schedule per ASIC
- ◆ Processing throughput of 10 Pentiums
- ◆ Power and performance similar to custom ASICs >3 GFLOPS/W
- ◆ Programmable and Scaleable
- ◆ Balanced I/O & Processing uniquely suited to Signal Processing needs

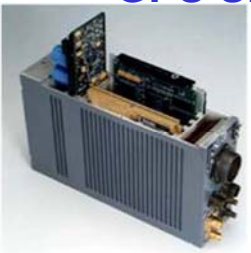
**System-on-a-Chip:**  
 Standalone solution for embedded applications  
*Enabler for ultra small UAVs, hand-helds, munitions, etc.*



**Tiled Array: TFLOP performance in a self-contained network**  
*Enabler for embedded advanced, adaptive signal processing*



### GPS SDR



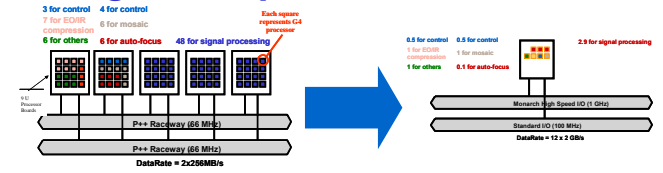
- Current anti-jam implementation...
- 1 Custom ASIC
  - 2 Vertex II Pro FPGAs
  - TMS-320  $\mu$ P
  - Flash Memory
  - RAM

*...Replaced by a single MONARCH chip!*

*Provides completely programmable solution  
 → Potential for future algorithm upgrades*



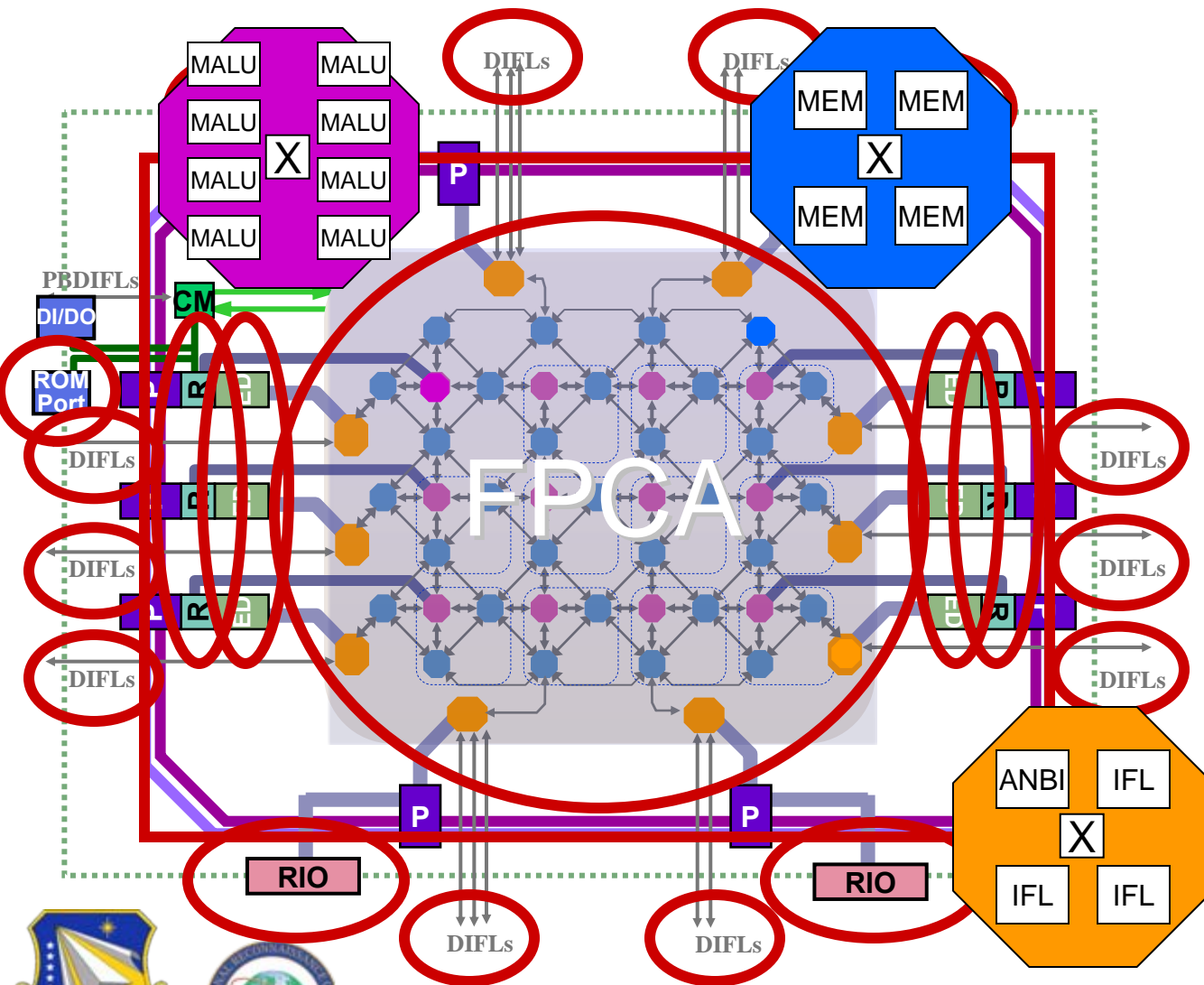
**MONARCH board provides >5x improvement in processing throughput, weight, and power for Global Hawk**







# Monarch Chip Overview



- ◆ 6 RISC Processors
- ◆ 12 MBytes on-chip DRAM
- ◆ 2 DDR-2 External Memory Interfaces (8 GB/s BW)
- ◆ Flash Port
- ◆ 2 Serial RapidIO Interface
- ◆ 16 IFL ports (2.6 GB/s ea)
- ◆ On-chip Ring 40 GB/s
- ◆ Reconfigurable Array – FPCA (64 GFLOPS)





# MONARCH Architecture Features



- ◆ **Dual native mode, high throughput computing**
  - Multiple wide word threaded (instruction flow) processors/chip
  - Highly parallel reconfigurable (data flow) processor
- ◆ **Flexible on-chip memories**
  - Multiport memory clusters
  - High bandwidth access to EDRAM
  - Extensible with off chip memory
- ◆ **High speed, distributed cross bar I/O**
  - Integrated with chip processing
  - Scalable I/O bandwidth - multiple topologies
  - Direct connect to high speed I/O devices, e.g., A/D's
- ◆ **Rich on chip interconnect**
  - Supports on chip topology morphing and fault tolerance
  - Supports multiple computation models (SISD, SIMD, DF, SPMD,...)
- ◆ **On chip Morph - Program bus and microcontrollers**





# Computation Attributes

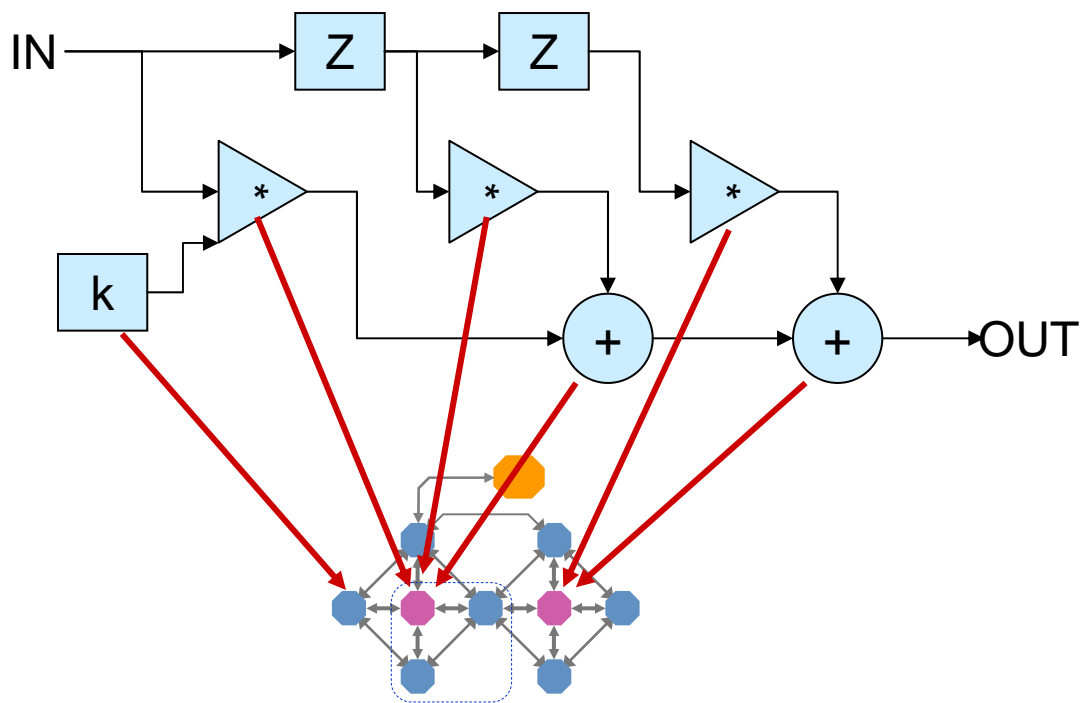


- ◆ **Fixed point arithmetic**
  - 8, 16, 32, and 40 bit arithmetic
  - Signed, unsigned, saturating modes
- ◆ **Floating point arithmetic**
  - 32 bit IEEE formats
- ◆ **SIMD and data flow control**
  - 256 bit SIMD data path (8 to 32 parallel ops)
  - >256 data flow elements per chip
- ◆ **In streaming mode, data tokens accompany each data element**
  - 2 bit field
  - Used for end of stream and other function control





# FPCA – Basic Paradigm



- ◆ FPCA contains multiple compute and memory resources within an interconnect fabric
- ◆ Static mapping of “operation” to H/W element (ALU/Multiplier/Memory)
- ◆ Distributed control (no central “controller”)
- ◆ Dynamic/data dependent operations supported



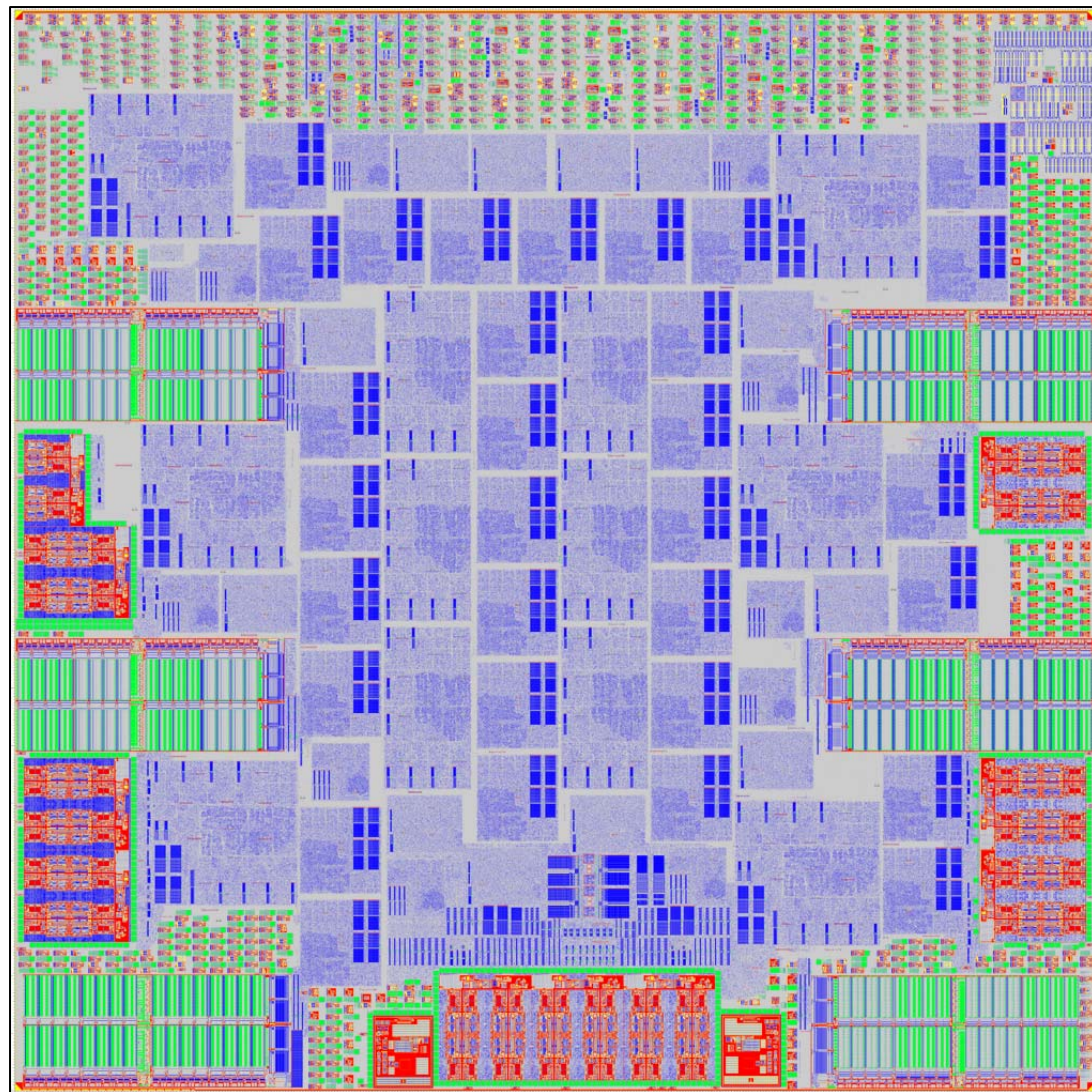




# MONARCH – Physical Design



- ◆ Standard cell ASIC
- ◆ 90 nm bulk CMOS
- ◆ 18.76mm x 18.76mm
- ◆ 280 million cells
- ◆ 10.5 million nets
- ◆ Over 1.5 km wire!!
- ◆ 1059 signal I/O
- ◆ 333 MHz
- ◆ 31- 42W
- ◆ Tape out Oct 10, 2006
- ◆ First silicon Dec 22

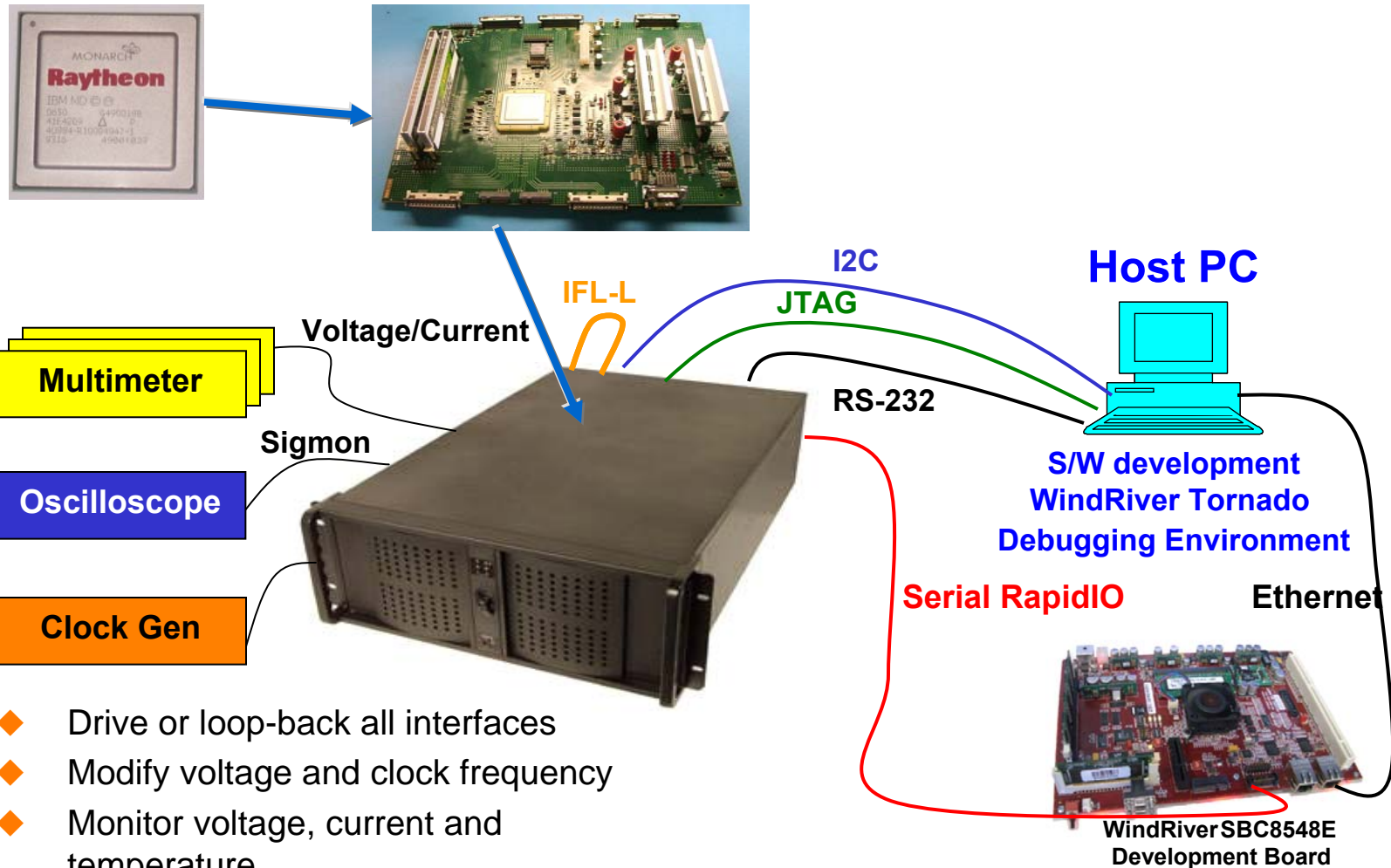


MONARCH





# MONARCH Chip Test Environment



- ◆ Drive or loop-back all interfaces
- ◆ Modify voltage and clock frequency
- ◆ Monitor voltage, current and temperature

◆ Identical S/W environment to Emulator

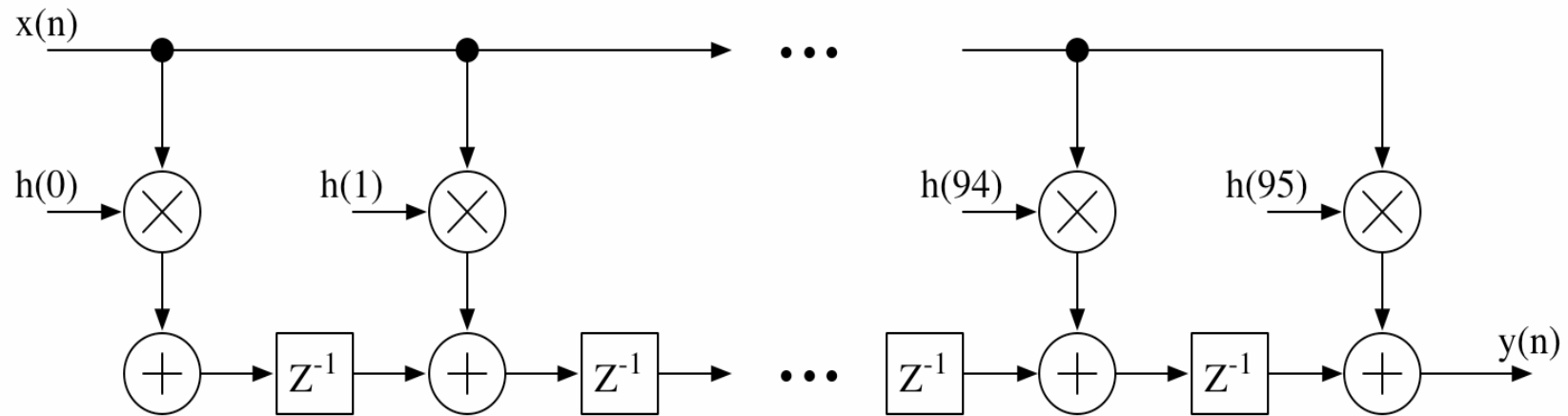




# FIR Filter Details



- ◆ FIR filter implemented using direct-form 2



- ◆ Directly maps to FPCA
- ◆ 96 Tap FIR Filter uses all 96 floating point adders and all 96 floating point multipliers
- ◆ Sustains full 333 MSamples/s giving 64 GFLOPS!
- ◆ Can also insert FIFOs to use all 124 memory elements (248 address generators)





# GFLOPS per Watt (FIR) Versus Process and Voltage



◆ 64 GFLOPS FIR Filter (no I/O, no FIFOs)

	<b>Low VDD (0.95v)</b>	<b>Nominal VDD (1.25V)</b>
<b>Faster Part (158ns PSRO)</b>	<b>5.8 GFLOPS/W (10.9W)</b>	<b>3.1 GFLOPS/W (20.9W)</b>
<b>Nominal Part (195ns PSRO)</b>	<b>6.6 GFLOPS/W (9.6W)</b>	<b>4.1 GFLOPS/W (15.6W)</b>

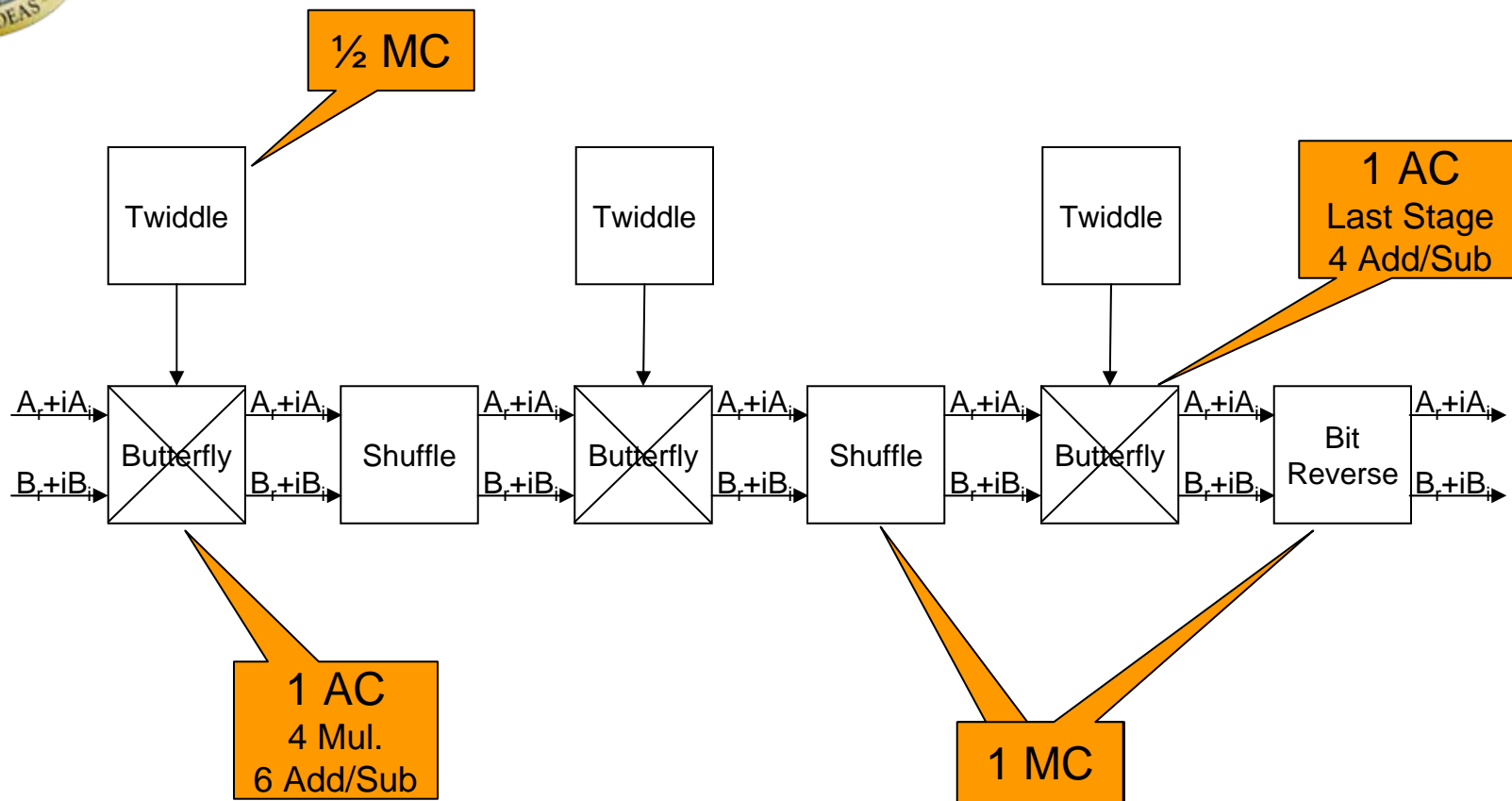
NOTE: The low Vdd operating condition is outside the chip design parameters







# FFT Implementation



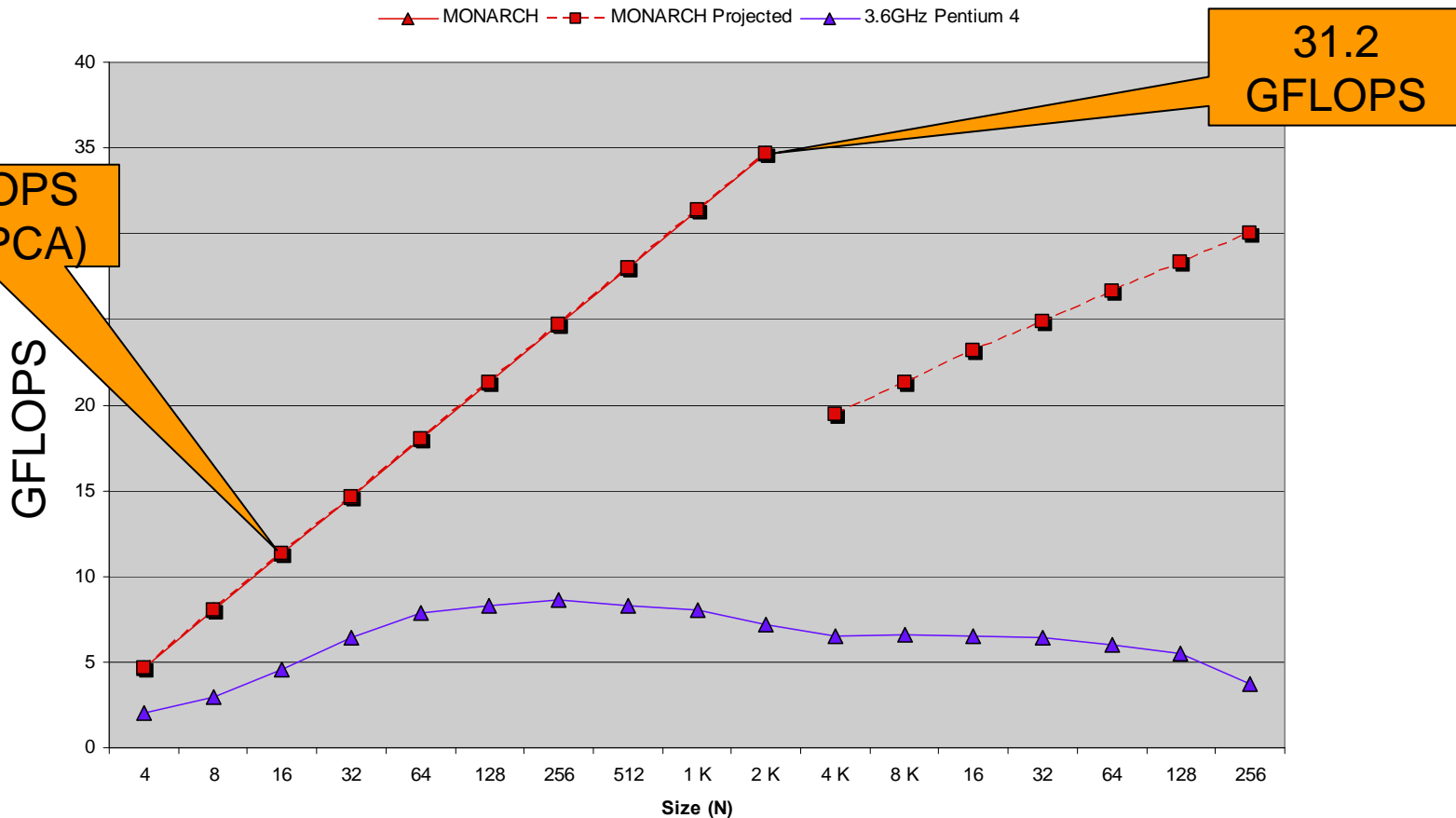
- ◆ **Input/Output: A = samples 0 to n/2-1, B = samples n/2 to n-1.**
- ◆ **For larger FFTs (512 to 2K), early stages and bit reverse need more MCs**
- ◆ **16 point uses 4 ACs – 3 instances can be mapped per FPCA**
- ◆ **2K point uses 11 ACs (maximum size due to extra MCs required)**





# MONARCH FFT Performance

MONARCH FFT Benchmark



34 GFLOPS  
(3 per FPCA)

31.2  
GFLOPS

- ◆ **MONARCH Notes...**
  - For  $N \leq 2048$ 
    - Radix-2 implementation
    - $N=16$  and  $N=2K$  verified on chip
  - For  $N > 2048$ 
    - Mixed-radix implementation
    - Performance is estimated, Currently being mapped and coded
- ◆ **Pentium Notes...**
  - Benchmark values gathered from FFTW web site
  - <http://www.fftw.org/speed/Pentium4-3.60GHz-icc/>





# GFLOPS per Watt (FFT) Versus Process and Voltage



- ◆ 2K Point FFT (31.2GFLOPS) (no I/O)
- ◆ For comparison IBM Cell is 0.5 GFLOP/W

	<b>Low VDD (0.95v)</b>	<b>Nominal VDD (1.25V)</b>
<b>Faster Part (158ns PSRO)</b>	<b>1.8 GFLOPS/W (17.6W)</b>	<b>1.3 GFLOPS/W (23.3W)</b>
<b>Nominal Part (195ns PSRO)</b>	<b>2.9 GFLOPS/S (10.7W)</b>	<b>2.6 GFLOPS/W (12.1W)</b>

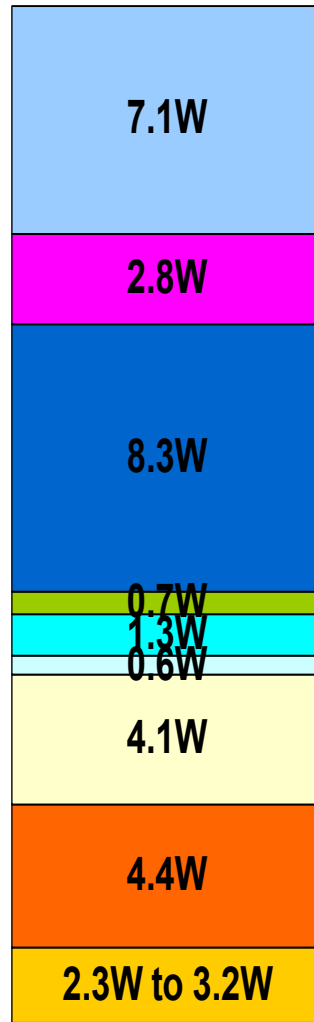
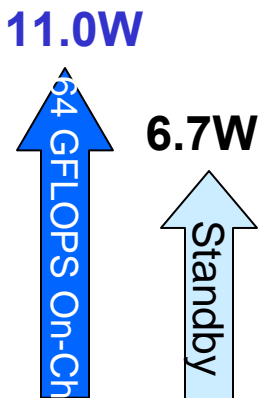
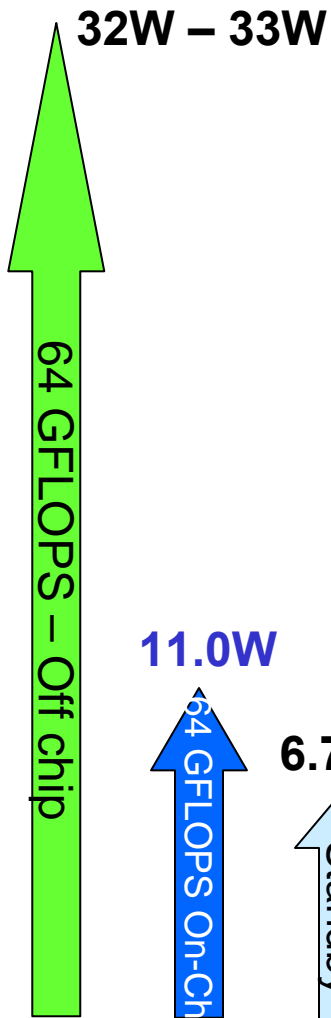
NOTE: The low Vdd operating condition is outside the chip design parameters







# MONARCH Power Measurements (Reduced Core Voltage, Nominal Part)



**External Memory – Dual Port 3.3 GB/s each  
(MMBT write test)**

**4 IFLL High speed I/O (2.6 GB/s)  
(IFLL bit error rate test)**

**12 IFLH High speed I/O (2.6 GB/s)  
(IFLH bit error rate test)**

**System I/O – Dual Rapid IO (estimate)  
All MMBT 13.3 (GB/s)  
All RISCs (2 GOPS)**

**All computing & memory elements 64 GFLOPS**

**Clocks, EDRAM refresh  
& infrastructure, Bi-Directional I/Os disabled**

**Leakage (30C to 70C)**

*NOTE: The low Vdd operating condition is outside the chip design parameters*





# MONARCH SW Tools



- ◆ **RISC C/C++ compiler**
  - Validated C++ compiler from Code Sourcery
  - Automatic vectorization for wide word (limited testing)
  - Supports gcc vector data types for the Wide Word processors
- ◆ **RISC assembler**
- ◆ **RISC Operating System**
  - RTEMS
  - Real-time, Embedded
  - Not validated on chip
- ◆ **RISC Libraries**
  - VSIPL Core Plus and SAL (for a single processor)
- ◆ **FPCA Libraries**
  - Signal processing routines (FFT, FIR)
- ◆ **FPCA tools**
  - Assembler, Router
- ◆ **Simulator**
  - Simulate FPCA and RISC
  - Gdb debugging for RISC programs





# Looking to the Future



- ◆ Improved software tools are essential
- ◆ Performance per Watt
- ◆ Lower total power
- ◆ Security/AT/Crypto
- ◆ Improved SWEPT for mission level enablers

<p><b><u>90 nm respin</u></b></p> <ul style="list-style-type: none"> <li>◆ Minor Errata Fix</li> <li>◆ Performance Same</li> </ul>	<p><b><u>45 nm respin with minimal mods</u></b></p> <ul style="list-style-type: none"> <li>◆ Leave chip design largely as is             <ul style="list-style-type: none"> <li>– New physical design</li> </ul> </li> <li>◆ Update IOs as needed</li> <li>◆ Update architecture paths</li> <li>◆ Performance per Watt 4X</li> <li>◆ Total performance 2X</li> </ul>	<p><b><u>45 nm respin with larger mods</u></b></p> <ul style="list-style-type: none"> <li>◆ Use 3D physical design and wafer scale</li> <li>◆ Plus those to left</li> <li>◆ Performance per Watt &gt;4X</li> <li>◆ Functionality/memory growth</li> <li>◆ Total performance &gt;2X</li> </ul>
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SWEPT

SWEPT

Size Weight Energy Performance Time



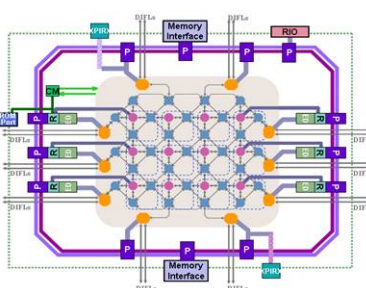
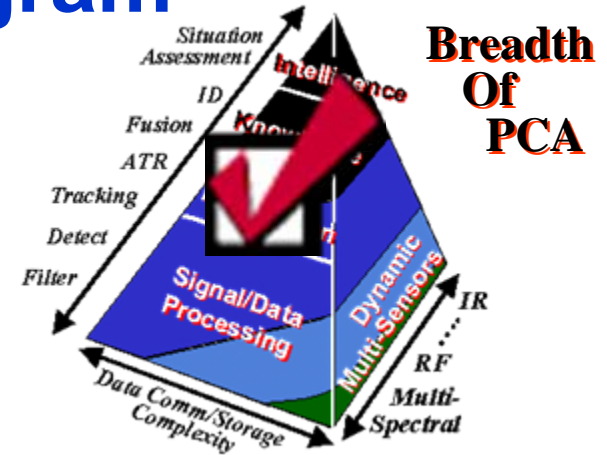




# Polymorphous Computing Architecture Program



**MONARCH Achieves DARPA Goals:**  
**Meets multi mission, multi sensor,**  
**high-efficiency processing with a**  
**single chip type**



### Sensors:

- Radar
- SIGINT
- Com
- EO/IR

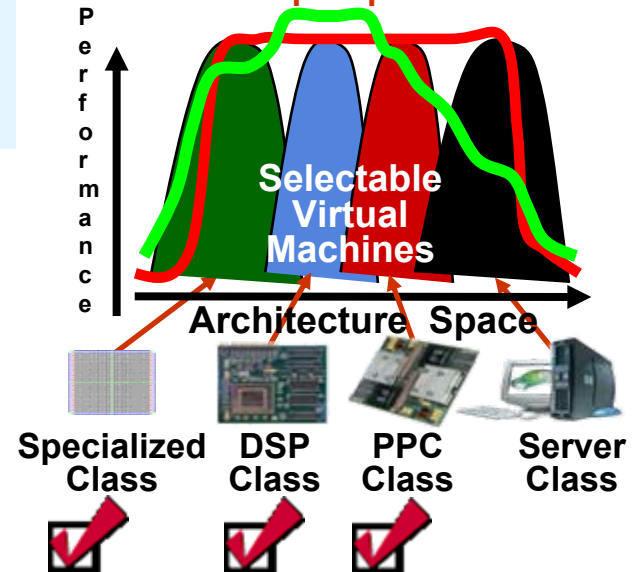
### Functions:

- Conditioning
- Beamforming
- Data creation
- Track
- Compression

### Replaces:

- ASIC
- FPGA
- DSP
- PPC

### PCA Morph Space - MONARCH



**Multi-Mission**

**Multiple Sensors (A,B,C...X) plug & play**

A B C... X

**In-Mission Re-targetability**

Platform trans it    Tracking Multi-sens or processing





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